

# LASER PROCESSING

## CIRCUIT BOARD MATERIALS

### LASER DEPANELING

- Keeps delicate components, soldered connections, & fragile substrates safe from any mechanical stress
- More value per panel due to minimal space between the boards

### LASER DRILLING

- Crucial for connecting circuitry between board layers
- Our lasers work directly from CAD data to drill through-holes, buried vias and blind vias

### LASER ROUTING

- Clean, burr-free cuts with no shape limitations
- Vaporizes materials rather than burning through them, allowing for maximum tolerance & repeatability

### LASER CUTTING FLEX CIRCUITS

- Delicate, clean & vibration-free cutting with minimal thermal influence
- Maintains the quality of the flexible Kapton material

